



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-02-22
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STP55H100SFY	BA7R*Z08PD5V	A	Z6IA	2020-02-22
	Amount	UoM	Unit type	ST ECOPACK Grade
	90.8	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	

Package Designator	Size	Nbr of instances	Shape	
QFF	6.5 - 4.6 - 1.1	3	flat	
Comment	PSMC-3L-EP			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.04	Die	407
Lead	2.90	Soft solder	31916

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.90	Soft solder	31916
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.898	Soft solder	924992

Material Composition Declaration :						Mfr Item Name	BA7R*Z08PD5V					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	2.502	mg	supplier	die	Silicon(Si)	7440-21-3		2.297	mg	918066	25297
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.133	mg	53157	1465
				supplier	metallisation	Gold(Au)	7440-57-5		0.005	mg	1999	55
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.037	mg	14788	407
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.005	mg	1998	55
				supplier	metallisation	Tungsten(W)	7440-33-7		0.005	mg	1998	55
				supplier	passivation	Silicon oxide	7631-86-9		0.020	mg	7994	220
Leadframe	M-004 Copper and its alloys	37.097	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		36.002	mg	970483	396498
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.965	mg	26012	10630
				supplier	alloy & coating	Phosphorus metal	7723-14-0		0.056	mg	1510	617
				supplier	alloy & coating	Zinc(Zn)	7440-66-6		0.074	mg	1995	815
				SVHC	solder	Lead (Pb)	7439-92-1	7a-Lead in high melting temper	2.898	mg	924992	31916
Soft solder	Solder	3.133	mg	supplier	solder	Tin (Sn)	7440-31-5		0.157	mg	50112	1729
				supplier	solder	Silver (Ag)	7440-22-4		0.078	mg	24896	859
				supplier	clip	Copper (Cu)	7440-50-8		8.647	mg	970483	95231
Clip	M-004 Copper and its alloys	8.910	mg	supplier	clip	Phosphorus (P)	7723-14-0		0.013	mg	1459	143
				supplier	clip	Iron (Fe)	7439-89-6		0.232	mg	26038	2555
				supplier	clip	Zinc(Zn)	7440-66-6		0.018	mg	2020	198
				supplier	mold compound	Amourphous Silica	60676-86-0		30.008	mg	799957	330485
Encapsulation	M-011 Other inorganic materials	37.512	mg	supplier	mold compound	Solid Epoxy Resin 1	223769-10-6		2.063	mg	54996	22720
				supplier	mold compound	Solid Epoxy Resin 2	85954-11-6		3.189	mg	85013	35121
				supplier	mold compound	Phenol Resin	205830-20-2		1.313	mg	35002	14460
				supplier	mold compound	Carbon Black	60676-86-0		0.188	mg	5012	2070
				supplier	mold compound	Crystalline Silica	14808-60-7		0.751	mg	20020	8271
connections coating	Solder	1.646	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.646	mg	1000000	18128